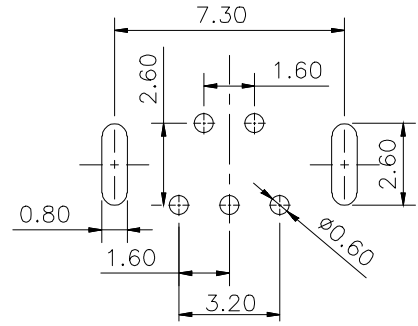
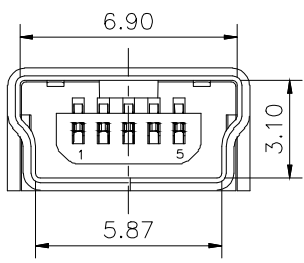
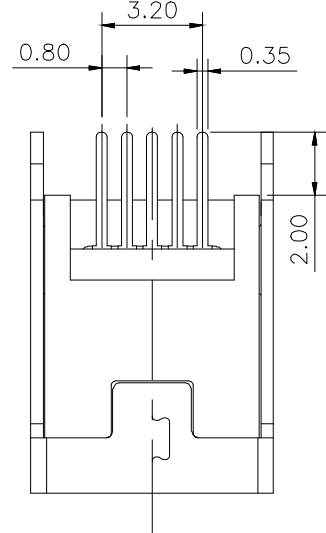
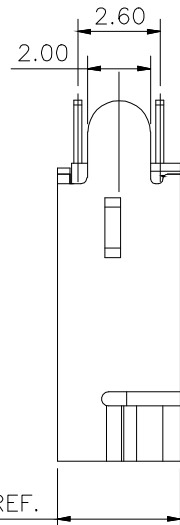
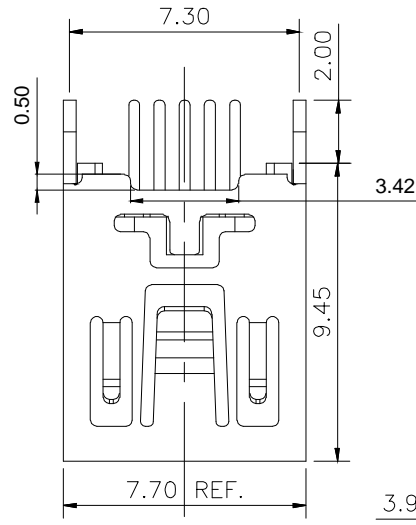


① **USB2.0 COMPLIANT**




RECOMMENDED PCB LAYOUT(T=1.00)

**NOTES:**

- 1. Material:
  - 1.1 Housing: LCP+30%GF UL94V-0, Color Black
  - 1.2 Shell: Brass T=0.40mm
  - 1.3 Contact :Brass T=0.25mm
- 2. FINISH:
  - 2.1 Contact Area: Gold Flash
  - Solder Area: Tin Plated
  - Under: Ni Plated
  - 2.2 Shell: 80u"Min Ni Plated
- 3. MECHANICAL:
  - 3.1 Mating Force: 3.0kgf Max.
  - 3.2 Unmating Force: 0.7kgf Min
- ② 3.3 Durability: 5000 cycles Min.
- 4. ELECTRICAL:
  - ③ 4.1 Current Rating: 1.8A Max
  - 4.2 Dielectric Strength: 300V AC FOR 1 MINUTE
  - 4.3 Contact Resistance: 50mΩ Max
  - 4.4 Insulation Resistance: 100 MΩ Min
  - ② 4.5 Voltage Rating: 30VAC
- 5. Operating temperature: -55°C TO +85°C
- ② Soldering temperature: +235°C, 5s max.
- 6. PACKIING: Tray

**RoHS compliant**  
Unit: mm

Scale	Free					Date	Name	Customer-No.
<b>TOLERANCE</b>						Drawn	07.08.2018	Xavier
.X	±0.30							
.XX	±0.20	③	Update current rating	12.05.2020	Luca	Approved	12.05.2020	Luca
.XXX	±0.10	②	Update	15.11.2019	Carson			
DIM	TOL	①	Update	15.08.2019	Xavier			
Angle	±1°	①	Update	15.08.2019	Xavier			
		①	Drawn	07.08.2018	Xavier	ASSMANN WSW components		ASSMANN WSW-No. <b>AUSB2-BFM-HTP1</b>
		Id.	Modification	Date	Name	Replace		Drawing-No. <b>ASS 8119 CO</b>
								rev03 Sheet